



M5M51004P,J-35,-45

1049576-BIT(262144-WORD BY 4-BIT) CMOS STATIC RAM

The M5M51004 is a family of 262144-word by 4-bit static RAMs, fabricated with the high performance CMOS silicon gate process and designed for high-speed application. These devices operate on a single 5V supply, and are TTL compatible. They include power down feature as well.

- Fast access time M5M51004P, J-35 35ns (max)
M5M51004P, J-45 45ns (max)
- Low power dissipation Active 400mW (typ)
Stand by 5mW (typ)
- Power down by $\overline{S}$
- Single 5V power supply
- Fully static operation
- Requires neither external clock nor refreshing
- All inputs and outputs are directly TTL compatible
- Easy memory expansion by $\overline{S}$
- OE prevents data contention in the I/O bus

High-speed memory systems

Pin diagram of the M5M5100AF/5100AJ memory chip. The chip is shown as a rectangle with pins numbered 1 to 28. Pins 1-13 are on the left, and pins 14-28 are on the right. Pin 14 is the center bottom pin. Pin 1 is VCC (5V). Pins 2-13 are ADDRESS INPUTS (A0-A12). Pin 12 is CHIP SELECT INPUT S. Pin 13 is OUTPUT ENABLE OE. Pin 14 is (0V) GND. Pins 15-19 are DATA I/O (DQ0-DQ4). Pin 20 is NC. Pins 21-24 are ADDRESS INPUTS (A14-A17). Pins 25-27 are ADDRESS INPUTS (A18-A20). Pin 28 is VCC (5V).

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FUNCTION

A write operation is executed during the $\bar{S}$ low and $\bar{W}$ low overlap time. In this period address signals must be stable. When $\bar{W}$ is low, the DQ terminals are maintained in the high impedance state, so it is possible to connect D and Q terminal directly.

In a read operation, after setting $\bar{W}$ to high, and $\bar{S}$ and $\bar{OE}$ to low if the address signals are stable, the data is available at DQ terminal.

When $\bar{S}$ is high, the chip is the non-selectable state, disabling both reading and writing. In this case, the output is in the floating (high-impedance) state, useful for OR-tie with other devices.

Setting the $\bar{OE}$ at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

Signal $\bar{S}$ controls the power-down features. When $\bar{S}$ goes high, power dissipation is reduced extremely. The access time from $\bar{S}$ is equivalent to the address access time.

FUNCTION TABLE

$\bar{S}$	$\bar{W}$	$\bar{OE}$	Mode	DQ	I_{CC}
H	X	X	Not select	Hi-Z	Stand by
L	L	X	Write	D _{in}	Active
L	H	L	Read	D _{out}	Active
L	H	H		Hi-Z	Active

Note: H: V_{IH} , L: V_{IL} , X: Don't care

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Units
V_{CC}	Supply voltage	With respect to GND	$-3.5 \sim 7$	V
V_I	Input voltage		$-3.5 \sim 7$	V
V_O	Output voltage		$-3.5 \sim 7$	V
P_d	Power dissipation		1	W
T_{opr}	Operating temperature		$0 \sim 70$	°C
T_{stg}	Storage temperature		$-65 \sim +150$	°C

* Pulse width ≤ 20 ns, in case of DC. ~ 0.5 V

DC ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Units
			Min	Typ	Max	
V_{IH}	High-level input voltage		2.4		$V_{CC} + 0.3$	V
V_{IL}	Low-level input voltage		-0.5^*		0.6	V
V_{OH}	High-level output voltage	$I_{OH} = -4\text{mA}$	2.4			V
V_{OL}	Low-level output voltage	$I_{OL} = 8\text{mA}$			0.4	V
I_I	Input current	$V_I = 0 \sim V_{CC} + 0.3\text{V}$			2	μA
I_{OZ}	Off-state output current	$V_I(s) = V_{IH}$, $V_O = 0 \sim V_{CC}$			10	μA
I_{CC1}	Supply current from V_{CC}	$V_I(s) = V_{IL}$, Output: open	AC (Min cycle)		120 ^N	mA
			DC	60	75	mA
I_{CC2}	Standby current	$V_I(s) = V_{IH}$	AC (Min cycle)		40	mA
			DC		30	mA
I_{CC3}	Stand by current	$V_{IS} \geq V_{SS} - 0.2\text{V}$, other $V_I \leq 0.2\text{V}$ or $V_I \geq V_{CC} - 0.2\text{V}$		1	10	mA

* -3.0V in case of AC (Pulse width ≤ 20 ns)

CAPACITANCE ($T_a = 0 \sim 70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Units
			Min	Typ	Max	
C_I	Input capacitance	$V_I = \text{GND}$, $V_t = 25\text{mVrms}$, $f = 1\text{MHz}$			5	pF
$C_{I/O}$	Input output capacitance	$V_{I/O} = \text{GND}$, $V_{I/O} = 25\text{mVrms}$, $f = 1\text{MHz}$			5	pF

Note: 1: Current flowing into an IC is positive, out is negative

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AC ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted.)

(1) MEASUREMENT CONDITIONS

Input pulse level $V_{IH} = 3V$, $V_{IL} = 0V$
 Input rise and fall time 3ns
 Input timing reference level $V_{IH} = 2.4V$, $V_{IL} = 0.6V$
 Output timing reference level . . . $V_{OH} = 2V$, $V_{OL} = 0.8V$

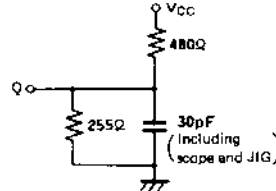


Fig. 1 Output load

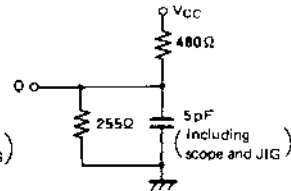


Fig. 2 Output load for ten, t_{dis}

(2) READ CYCLE

Symbol	Parameter	Limits						Units
		M5M51004-35			M5M51004-45			
		Min	Typ	Max	Min	Typ	Max	
t _{RC} (R)	Read cycle time	35			45			ns
t _a (A)	Address access time			35			45	ns
t _a (S)	Chip select access time			35			45	ns
t _a (OE)	Output enable access time			18			23	ns
t _v (A)	Data valid time after address	5			5			ns
t _{en} (S)	Chip selection to output active	5			5			ns
t _{dis} (S)	Output disable time from $\bar{S}$ high	0		20	0		20	ns
t _{en} (OE)	Output enable time after $\bar{OE}$ low	0			0			ns
t _{dis} (OE)	Output disable time after $\bar{OE}$ high	0		10	0		15	ns
t _{pu}	Power-up time after chip selection	0			0			ns
t _{pd}	Power-down time after chip selection			35			45	ns

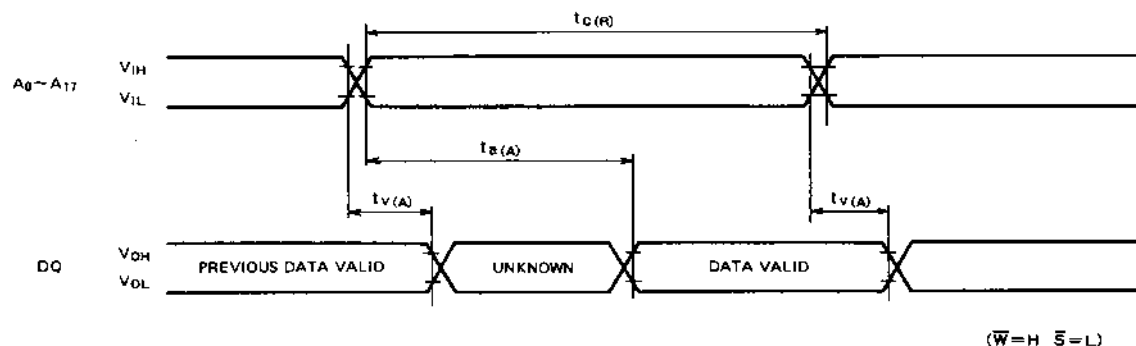
(3) WRITE CYCLE

Symbol	Parameter	Limits						Units
		M5M51004-35			M5M51004-45			
		Min	Typ	Max	Min	Typ	Max	
$t_{C(W)}$	Write cycle time	35			45			ns
$t_{su(S)}$	Chip select setup time	30			35			ns
$t_{su(A)1}$	Address setup time ($\bar{W}$)	0			0			ns
$t_{su(A)2}$	Address setup time ($\bar{S}$)	0			0			ns
$t_{W(W)}$	Write pulse width	30			35			ns
$t_{rec(W)}$	Write recovery time	5			5			ns
$t_{su(D)}$	Data setup time	15			20			ns
$t_h(D)$	Data hold time	0			0			ns
$t_{dis(W)}$	Output disable time from $\bar{W}$	0		15	0		15	ns
$t_{en(W)}$	Output enable time from $\bar{W}$	0			0			ns
$t_{su(A-WH)}$	Address to $\bar{W}$ high	30			35			ns
$t_{dis(OE)}$	Output disable time after $\bar{OE}$ high	0		10	0		15	ns
$t_{en(OE)}$	Output enable time after $\bar{OE}$ low	0			0			ns

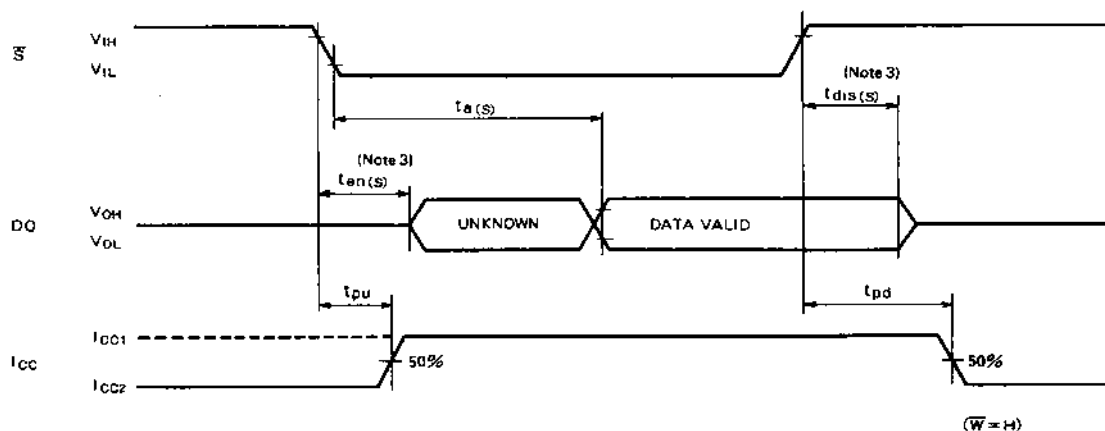
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(4) TIMING DIAGRAMS FOR READ CYCLE

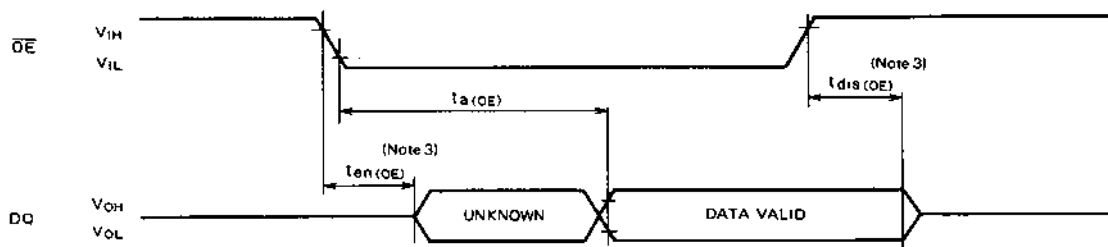
Read cycle 1



Read cycle 2 (Note 2)



Read cycle 3 (Note 4)

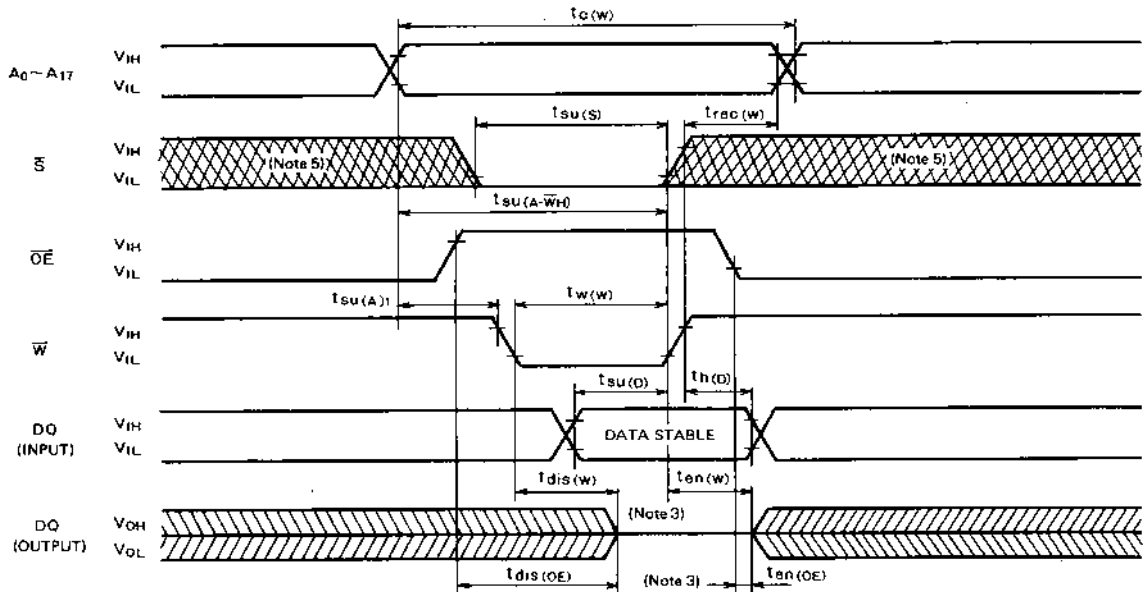


- Note 2: Addresses valid prior to or coincident with $\overline{S}$ transition low.
 Note 3: Transition is measured $\pm 500\text{mV}$ from steady state voltage with specified loading in Fig. 2.
 Note 4: Address and $\overline{S}$ valid prior to $\overline{OE}$ transition low by $(t_{A(A)} - t_{A(OE)}), (t_{V(S)} - t_{V(OE)})$.

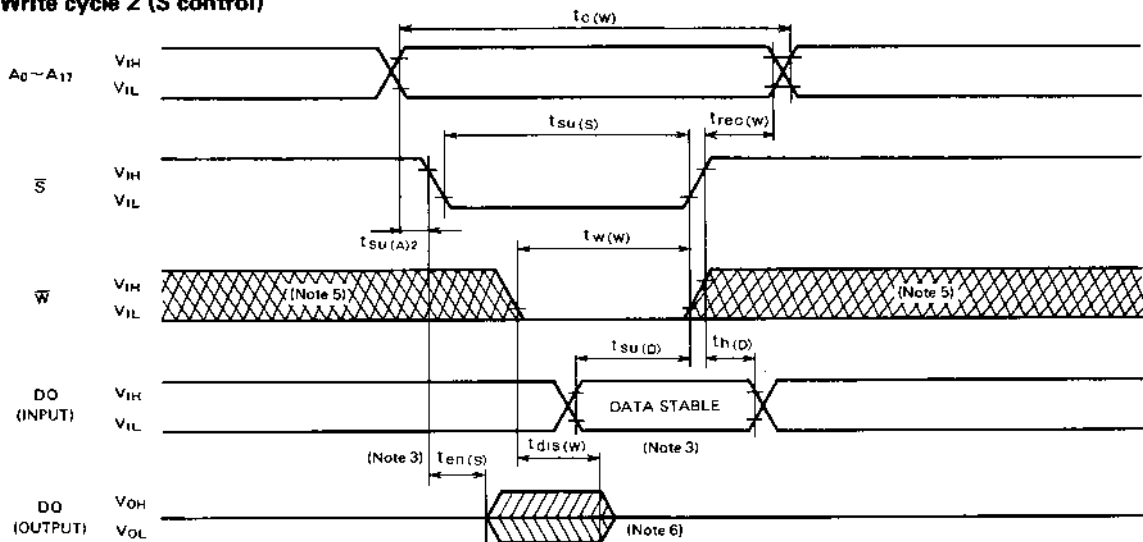
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(5) TIMING DIAGRAMS FOR WRITE CYCLE

Write cycle 1 ($\overline{W}$ control)



Write cycle 2 ($\overline{S}$ control)



Note 5: Hatching indicates the states don't care.

6: When the falling edge of $\overline{W}$ is simultaneously or prior to the falling edge of $\overline{S}$, the outputs are maintained in the high impedance.